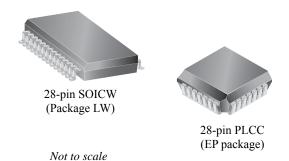


#### **Features and Benefits**

- Controlled output slew rate
- High-speed data storage
- 60 V minimum output break down
- High data-input rate
- PNP active pull-downs
- Low output-saturation voltages
- Low-power CMOS logic and latches
- Improved replacements for TL5812x, UCN5812x, and UCQ5812x

### Package:



#### **Description**

The A6812 device combines a 20-bit CMOS shift register, accompanying data latches and control circuitry with bipolar sourcing outputs ,and PNP active pull-downs. Designed primarily to drive vacuum-fluorescent displays, the 60 V and -40 mA output ratings also allow these devices to be used in many other peripheral power driver applications. The A6812 features an increased data-input rate (compared with the older UCN/UCQ5812-F) and a controlled output slew rate.

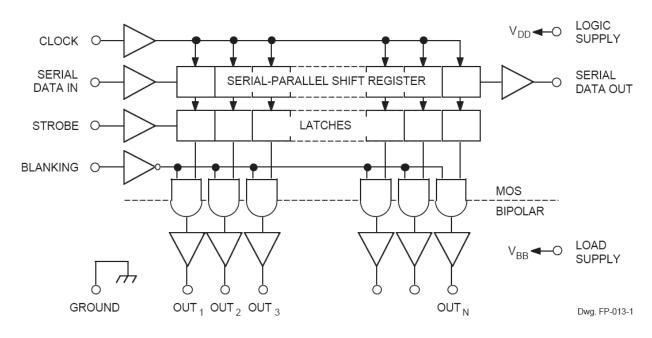
The CMOS shift register and latches allow direct interfacing with microprocessor-based systems. With a 3.3 or 5 V logic supply, they operate to at least 10 MHz.

A CMOS serial data output permits cascaded connections in applications requiring additional drive lines. Similar devices are available as the A6810 (10-bit) and A6818 (32-bit).

The A6812 output source drivers are NPN Darlingtons, capable of sourcing up to 40 mA. The controlled output slew rate reduces electromagnetic noise, which is an important consideration in systems that include telecommunications and/or microprocessors and to meet government emissions

Continued on the next page...

### **Functional Block Diagram**



### A6812

### DABiC-IV 20-Bit Serial-Input Latched Source Driver

### **Description (continued)**

regulations. For inter-digit blanking, all output drivers can be disabled and all sink drivers turned on with a BLANKING input high. The PNP active pull-downs sink at least 2.5 mA.

Three temperature ranges are available for optimum performance in commercial (suffix S-), industrial (suffix E-), or automotive (suffix K-) applications. Package styles are provided for surface-mount SOIC (suffix -LW), or minimum-area surface-mount PLCC (suffix

-EP). Copper lead frames, low logic-power dissipation, and low output-saturation voltages allow these drivers to source 25 mA from all outputs continuously to more than 43°C (suffix -LW) or 61°C (suffix -EP).

Each package is available in a lead (Pb) free version, with 100% matte tin leadframe plating.

Selection Guide								
Part Number	Pb-free	Packing	Package	Ambient Temperature, T <sub>A</sub> (°C)				
A6812EEP-T	Yes	38 pieces/tube						
A6812EEPTR	_	900 pigggg/12 in real	PLCC					
A6812EEPTR-T	Yes	800 pieces/13-in. reel		-40 to 85				
A6812ELW-T	Yes	27 pieces/tube		<u>-4</u> 0 to 85				
A6812ELWTR	_	1000 pigggg/12 in roal	SOIC-W					
A6812ELWTR-T	Yes	1000 pieces/13-in. reel						
A6812KLW-T	Yes	27 pieces/tube						
A6812KLWTR	_	4000 minana/42 im manl	SOIC-W	-40 to 125				
A6812KLWTR-T	Yes	1000 pieces/13-in. reel						
A6812SEP-T	Yes	38 pieces/tube						
A6812SEPTR	_	000 min and /10 im made	PLCC					
A6812SEPTR-T	Yes	800 pieces/13-in. reel		–20 to 85				
A6812SLW-T	Yes	27 pieces/tube	SOIC W					
A6812SLWTR-T	Yes	1000 pieces/13-in. reel	SOIC-W					

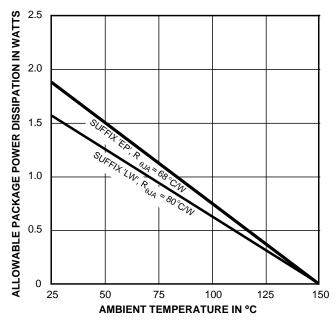


2

#### **Absolute Maximum Ratings\***

Characteristic	Symbol	Notes	Rating	Units
Logic Supply Voltage	V <sub>DD</sub>		7	V
Driver Supply Voltage	V <sub>BB</sub>		60	V
Input Voltage Range	V <sub>IN</sub>		$-0.3$ to $V_{DD} + 0.3$	V
Continuous Output Current Range	I <sub>OUT</sub>		-40 to 15	mA
		Range E	-40 to 85	°C
Operating Ambient Temperature	T <sub>A</sub>	Range K	-40 to 125	°C
		Range S	–20 to 85	°C
Maximum Junction Temperature	T <sub>J</sub> (max)		150	°C
Storage Temperature	T <sub>stg</sub>		-65 to 125	°C

<sup>\*</sup>Caution: These CMOS devices have input static protection (Class 2) but are still susceptible to damage if exposed to extremely high static electrical charges.



Dwg. GP-024-2

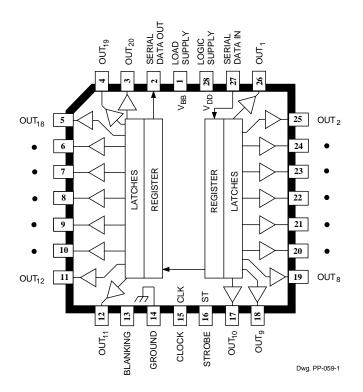
#### **Thermal Characteristics**

Characteristic	Characteristic Symbol Test Conditions*					
Package Thermal Resistance		Package EP, 1-layer PCB with solder limited to mounting pads	68	°C/W		
	$R_{ heta JA}$	Package LW, 1-layer PCB with solder limited to mounting pads	80	°C/W		

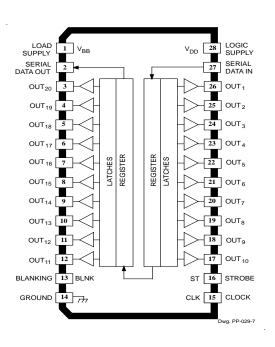
<sup>\*</sup>Additional thermal information available on the Allegro website



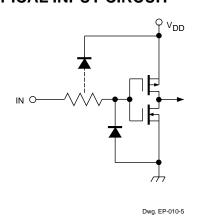
### **EP** Package



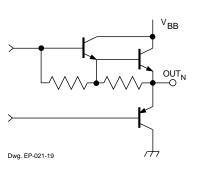
### **LW** Package



### **TYPICAL INPUT CIRCUIT**



#### **TYPICAL OUTPUT DRIVER**



### **TRUTH TABLE**

Serial			hift l	Regi	ister	Conte	ents	Serial			Lat	ch C	onte	ents				Out	tput (	Conte	ents	
Data Input	Clock Input	l	l <sub>2</sub>	l <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>	Data Output	Strobe Input	l <sub>1</sub>	l <sub>2</sub>	I <sub>3</sub>		I <sub>N-1</sub>	I <sub>N</sub>	Blanking	I <sub>1</sub>	l <sub>2</sub>	l <sub>3</sub> .	I <sub>N</sub>	-1	
IN	Г																					
Н	丁	Н	R <sub>1</sub>	$R_2$		R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>														
L	L	L	R <sub>1</sub>	R <sub>2</sub>		R <sub>N-2</sub>	R <sub>N-1</sub>	R <sub>N-1</sub>														
Х		R <sub>1</sub>	R <sub>2</sub>	R <sub>3</sub>		R <sub>N-1</sub>	R <sub>N</sub>	R <sub>N</sub>														
		X	Х	Х		Х	Χ	Х	L	R <sub>1</sub>	R <sub>2</sub>	R <sub>3</sub>		R <sub>N-1</sub>	R <sub>N</sub>							
		P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub>		P <sub>N-1</sub>	P <sub>N</sub>	PN	Н	P <sub>1</sub>	P <sub>2</sub>	P <sub>3</sub>		P <sub>N-1</sub>	$P_{N}$	L	P <sub>1</sub>	P <sub>2</sub>	Р3.	P	N-1 P	N
											~	~				ш						

L = Low Logic Level H = High Logic Level X = Irrelevant P = Present State R = Previous State



ELECTRICAL CHARACTERISTICS at  $T_A = +25$ °C (A6812S-) or over operating temperature range (A6812E- or A6812K-),  $V_{BB} = 60$  V; unless otherwise noted

			Limits	@ V <sub>DD</sub> :	= 3.3 V	Limits			
Characteristic	Symbol	Test Conditions	MIn.	Тур.	Max.	Min.	Тур.	Max.	Units
Output Leakage Current	I <sub>CEX</sub>	V <sub>OUT</sub> = 0 V	_	<-0.1	-15	_	<-0.1	-15	μΑ
Output Voltage	V <sub>OUT(1)</sub>	I <sub>OUT</sub> = -25 mA	57.5	58.3	_	57.5	58.3	_	V
	V <sub>OUT(0)</sub>	I <sub>OUT</sub> = 1 mA	_	1.0	1.5	_	1.0	1.5	V
Output Pull-Down Current	I <sub>OUT(0)</sub>	V <sub>OUT</sub> = 5 V to V <sub>BB</sub>	2.5	5.0	_	2.5	5.0	_	mA
Input Voltage	V <sub>IN(1)</sub>		2.2	_	_	3.3	_	_	V
	V <sub>IN(0)</sub>		_	_	1.1	_	_	1.7	V
Input Current	I <sub>IN(1)</sub>	V <sub>IN</sub> = V <sub>DD</sub>	_	<0.01	1.0	_	<0.01	1.0	μΑ
	I <sub>IN(0)</sub>	V <sub>IN</sub> = 0 V		<-0.01	-1.0	_	<-0.01	-1.0	μΑ
Input Clamp Voltage	V <sub>IK</sub>	I <sub>IN</sub> = -200 μA	_	-0.8	-1.5	_	-0.8	-1.5	V
Serial Data Output Voltage	V <sub>OUT(1)</sub>	I <sub>OUT</sub> = -200 μA	2.8	3.05	_	4.5	4.75	_	V
	V <sub>OUT(0)</sub>	I <sub>OUT</sub> = 200 μA	_	0.15	0.3	_	0.15	0.3	V
Maximum Clock Frequency	f <sub>c</sub>		10*	_	_	10*	_	_	MHz
Logic Supply Current	I <sub>DD(1)</sub>	All Outputs High	_	0.25	0.75	_	0.3	1.0	mA
	I <sub>DD(0)</sub>	All Outputs Low	-	0.25	0.75	_	0.3	1.0	mA
Load Supply Current	I <sub>BB(1)</sub>	All Outputs High, No Load	_	3.0	6.0	_	3.0	6.0	mA
	I <sub>BB(0)</sub>	All Outputs Low	_	0.2	20		0.2	20	μA
Blanking-to-Output Delay	t <sub>dis(BQ)</sub>	C <sub>L</sub> = 30 pF, 50% to 50%	_	0.7	2.0	_	0.7	2.0	μs
	t <sub>en(BQ)</sub>	C <sub>L</sub> = 30 pF, 50% to 50%	_	1.8	3.0	_	1.8	3.0	μs
Strobe-to-Output Delay	t <sub>p(STH-QL)</sub>	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	_	0.7	2.0	_	0.7	2.0	μs
	t <sub>p(STH-QH)</sub>	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	_	1.8	3.0	_	1.8	3.0	μs
Output Fall Time	t <sub>f</sub>	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	2.4	_	12	2.4	_	12	μs
Output Rise Time	t <sub>r</sub>	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	2.4	_	12	2.4	_	12	μs
Output Slew Rate	dV/dt	$R_L = 2.3 \text{ k}\Omega, C_L 30 \text{ pF}$	4.0	_	20	4.0	_	20	V/µs
Clock-to-Serial Data Out Delay	t <sub>p(CH-SQX)</sub>	I <sub>OUT</sub> = ±200 μA	_	50	_	_	50	_	ns

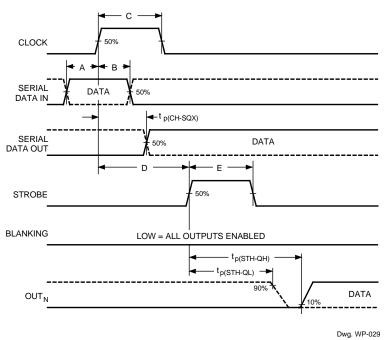
Negative current is defined as coming out of (sourcing) the specified device terminal.

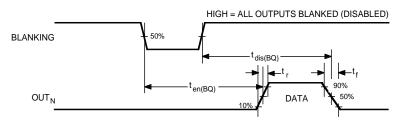
Typical data is is for design information only and is at  $T_A$  = +25°C.



<sup>\*</sup> Operation at a clock frequency greater than the specified minimum is possible but not warranteed.

# TIMING REQUIREMENTS and SPECIFICATIONS (Logic Levels are V<sub>DD</sub> and Ground)





Serial Data present at the input is transferred to the shift register on the logic "0" to logic "1" transition of the CLOCK input pulse. On succeeding CLOCK pulses, the registers shift data information towards the SERIAL DATA OUTPUT. The SERIAL DATA must appear at the input prior to the rising edge of the CLOCK input waveform.

Dwg. WP-030A

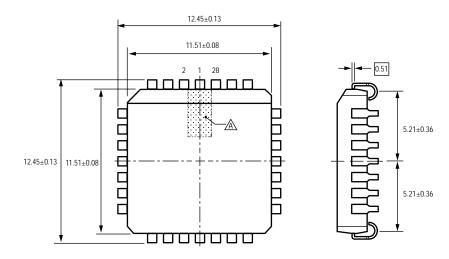
Information present at any register is transferred to the respective latch when the STROBE is high (serial-to-parallel conversion). The latches will continue to accept new data as long as the STROBE is held high. Applications where the latches are bypassed (STROBE tied high) will require that the BLANKING input be high during serial data entry.

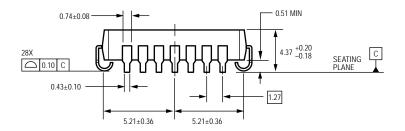
When the BLANKING input is high, the output source drivers are disabled (OFF); the pnp active pull-down sink drivers are ON. The information stored in the latches is not affected by the BLANKING input. With the BLANKING input low, the outputs are controlled by the state of their respective latches.



clock frequency.

### EP Package, 28-Pin PLCC



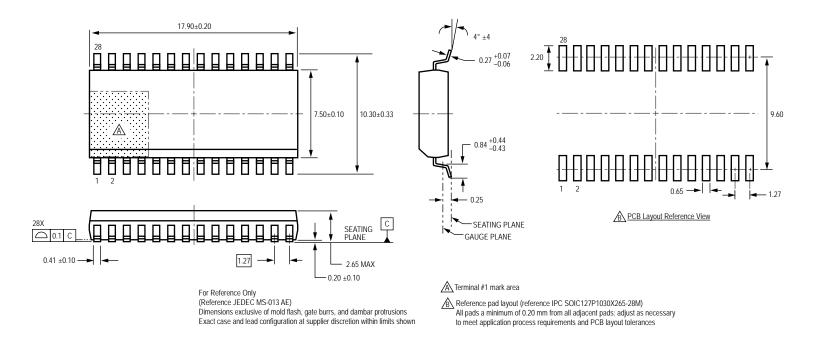


For Reference Only (reference JEDEC MS-018 AB)
Dimensions in millimeters
Dimensions exclusive of mold flash, gate burrs, and dambar protrusions
Exact case and lead configuration at supplier discretion within limits shown
Terminal #1 mark area



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### LW Package, 28-Pin SOICW



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